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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

| ATTY. DOCKET NO. 5542.02 | SERIAL NO. 09/957,401 | |
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| APPLICANT: Herbert J. NEUHAUS et al. | | |

FILING DATE
19 September 2001

GROUP Not Yet Assigned JQJ4

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| • • • | | (a) | | | | | Sheet 2 of 2 | |
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| • | FORM PTO-1449 (Modified) | U.S. DEPARTMENT OF C | 5542,02 | ATTY. DOCKET NO. SERIAL NO. 09/957,401 | | | | |
| | INFORMATION STATEMENT BY | DISCLOSURE APPLICANT | | APPLICANT: Herbert J. NEI | | | | |
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